



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUZ30N08S5N186	Issued	11. August 2021
MA#	MA005430857		
Package	PG-TSDSON-8-32	Weight*	35.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.310	0.88	0.88	8778	8778
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88	
	non noble metal	zinc	7440-66-6	0.012	0.04		352	
	non noble metal	iron	7439-89-6	0.249	0.70		7045	
	non noble metal	copper	7440-50-8	10.102	28.61	29.36	286052	293537
wire	noble metal	gold	7440-57-5	0.031	0.09	0.09	874	874
encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1056	
	plastics	epoxy resin	-	1.921	5.44		54397	
	inorganic material	silicondioxide	60676-86-0	16.693	47.26	52.81	472670	528123
leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11334	11334
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2425	2425
solder	non noble metal	tin	7440-31-5	0.010	0.03		271	
	noble metal	silver	7440-22-4	0.012	0.03		339	
	non noble metal	lead	7439-92-1	0.457	1.30	1.36	12952	13562
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2062	
	non noble metal	copper	7440-50-8	2.958	8.37	8.59	83746	85937
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			17	
	non noble metal	zinc	7440-66-6	0.002	0.01		67	
	non noble metal	iron	7439-89-6	0.047	0.13		1330	
	non noble metal	copper	7440-50-8	1.908	5.40	5.54	54016	55430
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com

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